

PRESS RELEASE

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FINETECH DEBUTS NEW FINEPLACER FEMTO^{BLU} MICRO ASSEMBLY CELL FOR PHOTONIC COMPONENT ASSEMBLY

FINETECH, a leading provider of precision bonders and advanced rework equipment, announces the latest addition to the FINEPLACER[®] family, the FINEPLACER[®] femto^{blu} bonding system. This automated micro assembly cell is an efficient and economical solution for dedicated photonic production. These demanding applications will benefit from a placement accuracy of 2.0 μm @ 3 Sigma and ultra-low force bonding capability down to 5 gram-force.

Designed for prototyping and high-yield production duties, the system supports all bonding technologies specifically required for the assembly of photonic and optoelectronic components. A complete machine enclosure minimizes external influences to ensure a stable process environment and protects the operator against gas, vapor and UV radiation.

The DualCam visual alignment system (with twin-camera module and beam splitter) provides application-specific fields of view, digital zoom, and various LED illumination options. It also delivers optics shifting along the X-axis for optimal viewing of a wide spectrum of component sizes.

IPM Command, the advanced FINEPLACER[®] operating software, supports a consistent, ergonomic and clearly structured process development. It enables the synchronized control of all process parameters and additional process modules and provides pattern recognition for the automated alignment of substrates and components based on their structures and patterns.

Depending on specific needs, the modular FINEPLACER[®] femto^{blu} can be individually configured and upgraded in-field to support additional applications and technologies. It covers the entire workflow of inspection, characterization, packaging, final test and qualification in the development and manufacturing of data communication products and beyond.

About Finetech

Finetech is a leading manufacturer of equipment for manual and fully automatic high-precision bonding and component rework. The company services customers in a broad range of industries including telecom/datacom, aerospace, automotive, medical technology, consumer electronics, semiconductor, military, universities and research. Corporate headquarters and main production are in Berlin, Germany. Sales and Technical support centers are located in Gilbert, Arizona; Amherst, New Hampshire; Shanghai, China; Kuala Lumpur, Malaysia; and Tokyo, Japan. www.finetechusa.com.



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